

AMENDMENTS TO THE CLAIMS:

Replacement Claim Set:

1. (Currently amended) An integrated circuit, comprising:

a substrate;

a porous dielectric layer disposed on the substrate and having a trench disposed therein;

a conductor disposed within the trench; and

~~a substantially impermeable barrier~~ pore sealing layer, including at least two different materials bonded together and expanded, located between the conductor and the dielectric layer.
2. (Original) The integrated circuit of Claim 1 wherein one of the materials includes palladium.
3. (Original) The integrated circuit of Claim 1 wherein one of the materials includes platinum.
4. (Currently amended) The integrated circuit of Claim 1 wherein ~~the barrier further~~ one of the materials includes silicon.
5. (Original) The integrated circuit of Claim 1 wherein the conductor includes copper.
6. (Currently amended) The integrated circuit of Claim 1 wherein the ~~barrier~~ pore sealing layer has a thickness between about 2 nm to about 200 nm.
7. (Canceled).
8. (Canceled).
9. (Canceled).
10. (Canceled).
11. (Canceled).

12. (Canceled).
13. (Canceled).
14. (Canceled).
15. (New) The integrated circuit of Claim 1 wherein at least one of the materials includes a dielectric material.
16. (New) The integrated circuit of Claim 1 additionally comprising a barrier material.
17. (New) The integrated circuit of Claim 1 wherein one of the materials is Pt and one of the materials is Si.
18. (New) The integrated circuit of Claim 1 wherein one of the materials is Pd and one of the material is Si.
19. (New) The integrated circuit of Claim 1 wherein the pore sealing layer completely seals the surface pores of the dielectric.
20. (Withdrawn) A method of making the integrated circuit of Claim 1 comprising forming a pore sealing layer on a porous dielectric.
21. (Withdrawn) The method of Claim 20 wherein forming a pore sealing layer comprises depositing a first material.
22. (Withdrawn) The method of Claim 21 wherein forming a pore sealing layer additionally comprises depositing a second material.